

SPECIFICATION

TFT LCD MODULE

MODEL NO:	TM057KVHG01
CUSTOMER:	
CUSTOMER P/N.	
VERSION	V0.1
CUSTOMER APPROVED	

- Preliminary specification
- Final specification

PREPARED BY	CHECKED BY	VERIFIED BY QA DEPT.	APPROVED BY

TIANMA MICRO-ELECTRONICS CO., LTD

Address: 8F, 64th Building, Jinlong, Majialong Industrial Area, Nanshan District, Shenzhen, China Tel:
+86-755-26094288 Fax: +86-755-86225774 Web: www.tianma.cn www.tianma.com

Table of Contents

1. General Specifications	3
2. Input/Output Terminals	5
2.1 TFTLCD pin assignment	5
2.2 Backlight pin assignment.....	6
2.3 CTP pin assignment.....	6
3. Absolute Maximum Ratings.....	6
4. Electrical Characteristics.....	7
4.1 Driving TFT LCD.....	7
4.2 Driving CTP.....	7
4.3 Driving Backlight.....	8
5. Block diagram.....	9
6. TFT Timing Chart.....	10
7. CTP Timing	14
8. Optical Characteristics	15
9. Reliability Test.....	18
10. Mechanical Drawing.....	20
11. Product Inspection Criteria	21
12. Precautions for Use of LCD Modules	26
13. Packing	28
14. Product part number system	29

1 General Specifications

TM057KVHG01 is a color active matrix LCD module incorporating amorphous silicon TFT (Thin Film Transistor). It is composed of a color TFT-LCD panel, driver IC, FPC, a back light unit and CTP (Capacitive Touch Panel) with Multi-Touch function. The mounting method is with tape bonding . This product accords with RoHS environmental criterion.

Item	Feature	Spec	Unit	Note	
TFT LCD Module	Size	5.7	inch		
	LCD Resolution	320(RGB) x 240	--		
	Interface	TFT LCD : RGB 18 bits		--	
		CTP:I2C			
	Color Depth	262K	--		
	LCD Technology Type	a-Si TFT	--		
	Pixel Pitch	0.360x0.360	mm		
	Pixel Configuration	R.G.B. Vertical Stripe	--		
	LCD display Mode	TM with Normally White	--		
	Surface Treatment	CTP:6H hardness		--	
		LCD Up Polarizer:AG(3H)			
	Viewing Direction	6 o'clock	--		
	Gray Scale Inversion Direction	12 o'clock	--		
	Active Area	TFTLCD: 144.00(W)x104.60(H)		mm	
		CTP:119.20(W)x90.40(H)		mm	
	LCM (W x H x D)	144.00x104.60x12.30		mm	
	Control IC	CTP: NT11003		--	
		TFT LCD:NT39413		--	
	CTP Touch Method	Bare finger		--	
	Number of simultaneous touches	2 points		--	
	Minimum Touch Area	Φ6		mm	
	Finger Touch Pitch	15		mm	
	CTP Structure	Glass Lens - Glass Sensor		--	
LED Numbers	15LEDs		pcs		
Weight	TBD		g		

2. Input/Output Terminals

2.1 TFT LCD Pin Assignment

Connector type: 089H33-000100-G2-R (STARCONN)

No	Symbol	I/O	Description	Comment
1	GND	P	Ground	
2	CK	I	Dot clock. Latch data at falling edge of CK.	
3	Hsync	I	Horizontal sync signal in SYNC mode. Pull low or floating when DE mode.	
4	Vsync	I	Vertical sync signal in SYNC mode. Pull low or floating when DE mode.	
5	GND	P	Ground	
6	R0	I	Red data (LSB)	
7	R1	I	Red data	
8	R2	I	Red data	
9	R3	I	Red data	
10	R4	I	Red data	
11	R5	I	Red data (MSB)	
12	GND	P	Ground	
13	G0	I	Green data(LSB)	
14	G1	I	Green data	
15	G2	I	Green data	
16	G3	I	Green data	
17	G4	I	Green data	
18	G5	I	Green data(MSB)	
19	GND	P	Ground	
20	B0	I	Blue data(LSB)	
21	B1	I	Blue data	
22	B2	I	Blue data	
23	B3	I	Blue data	
24	B4	I	Blue data	
25	B5	I	Blue data(MSB)	
26	GND	P	Ground	
27	ENAB	I	Data enable signal in DE mode. This pin must pull high when SYNC mode.	
28	VCC	P	Power supply	
29	VCC	P	Power supply	
30	R/L	I	Set horizontal scan direction: Low/NC: left to right; High: right to left	
31	U/D	I	Set vertical scan direction: High/NC: up to down; Low: down to up	
32	NC	-	No connection	
33	GND	P	Ground	

Note1: I/O definition:

I----Input O----Output P----Power/Ground

Note2: CN1 Matching FPC type: 33 pin, pitch: 0.5mm, height: 0.3mm.

2.2 Backlight Pin Assignment

Connector type: SHLP-06V-S-B (JST)

No	Symbol	I/O	Description	Comment
1	AN1	P	LED Anode Terminal	Red
2	AN2	P	LED Anode Terminal	Red
3	AN3	P	LED Anode Terminal	Red
4	CA1	P	LED Cathode Terminal	White
5	CA2	P	LED Cathode Terminal	Blue
6	CA3	P	LED Cathode Terminal	Black

Note1: CN2 Matching Connector type: SM06B-SHLS-TF (JST)

Note2:P: Power/GND; I: input pin; I/O: input or output pin;

2.3 CTP Pin Assignment

Pin No.	Symbol	I/O	Description	Remark
1	GND	P	Groud	
2	RESET	I/O	External interrupt from the host	
3	VDD	P	CTP power supply	
4	INT	I/O	External interrupt to the host	
5	SCL	I/O	I2C clock input	
6	SDA	I/O	I2C data input and output	
7	H_SYNC	I/O	External singal from LCD	
8~10	NC	NC	NC	

Note: I/O definition.

I---Input, O---Output, P--- Power/Ground, N--- No connection

3. Absolute Maximum Ratings

Ta = 25°C

Item	Symbol	Min	Max	Unit	Remark
Power Voltage	VCC(LCD)	-0.3	5	V	
	VDD(CTP)	-0.3	3.6	V	
	AN1,AN2,AN3 (backlight)	0	25.9	V	
Operating Temperature	TOPR	-20	70	°C	
Storage Temperature	TSTG	-30	80	°C	Note1

Table 3.1 absolute maximum rating

Note1: 80°C is the surface temperature of module

Electrical Characteristics

4.1 .1 Driving TFT LCD

Ta = 25°C

Item	Symbol	Min	Typ	Max	Unit	Remark
Voltage for logic circuit	VCC	3.0	3.30	3.60	V	
Power supply current	ICC	--	145	225	mA	
Input Signal Voltage	Low Level	VIL	0	-	0.3xVDD	R0~R5, G0~G5, B0~B5, CK, DISP, HSYNC, VSYNC, ENAB,R/L,U/D
	High Level	VIH	0.7xVDD	-	VDD	

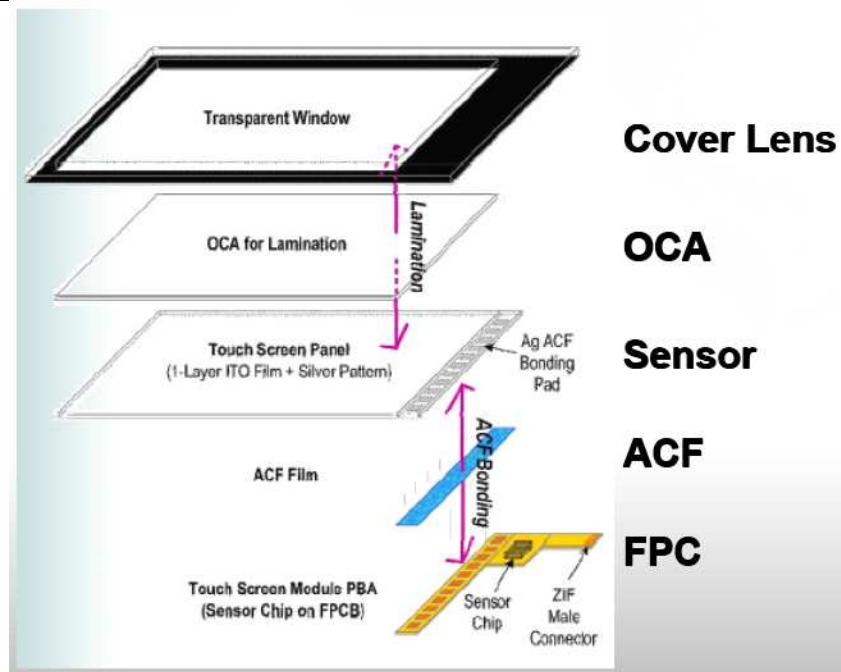
Table 4.1 LCD module electrical characteristics

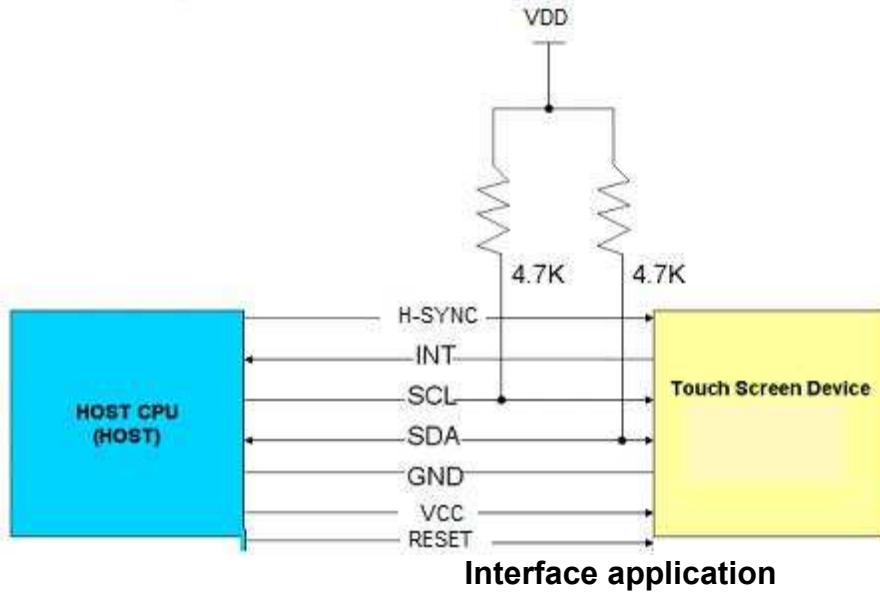
Note: To test the current dissipation, use "all Black Pattern".

4.1 .2 Driving CTP

Ta = 25°C

Item	Min	Typ	Max	Unit	Note
power supply voltage	2.7	3.3	3.6	V	DC(noise should be under 100mV)
Power supply current	--	6	10	mA	
Input Signal Voltage	Low Level	0	-	0.3xVCC	INT,RESETP,SCL,SDA, H-SYNC
	High Level	0.7xVCC	-	VCC	


Structure of touch lens



4.1.3 Driving Backlight

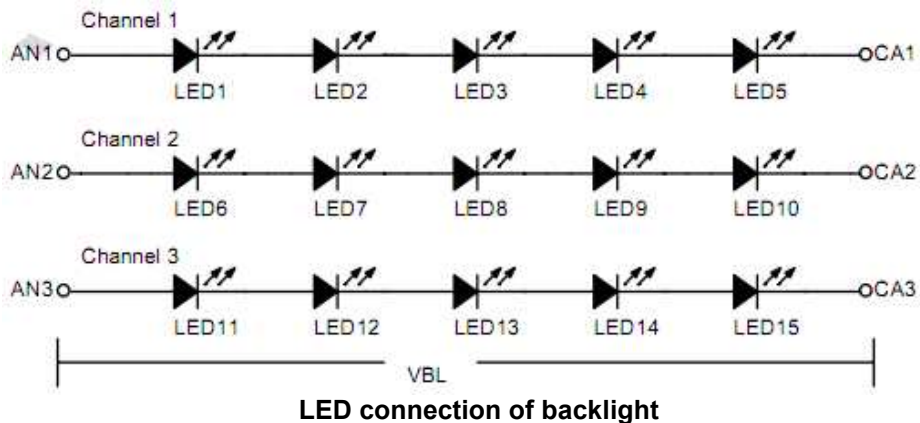
Item	Symbol	Min	Typ	Max	Unit	Remark
Channel1	$I_{channel\ 1}$	-	25.0	-	mA	Note 1
Channel2	$I_{channel\ 2}$	-	25.0	-	mA	
Channel3	$I_{channel\ 3}$	-	25.0	-	mA	
Forward Voltage	V_{BL}	14.85	-	18.15	V	
Backlight Power Consumption	W_{BL}	-	1,238	-	mW	
Life Time	-	25,000	(50,000)		Hrs	Note 3

Table 4.1.3 LED backlight characteristics

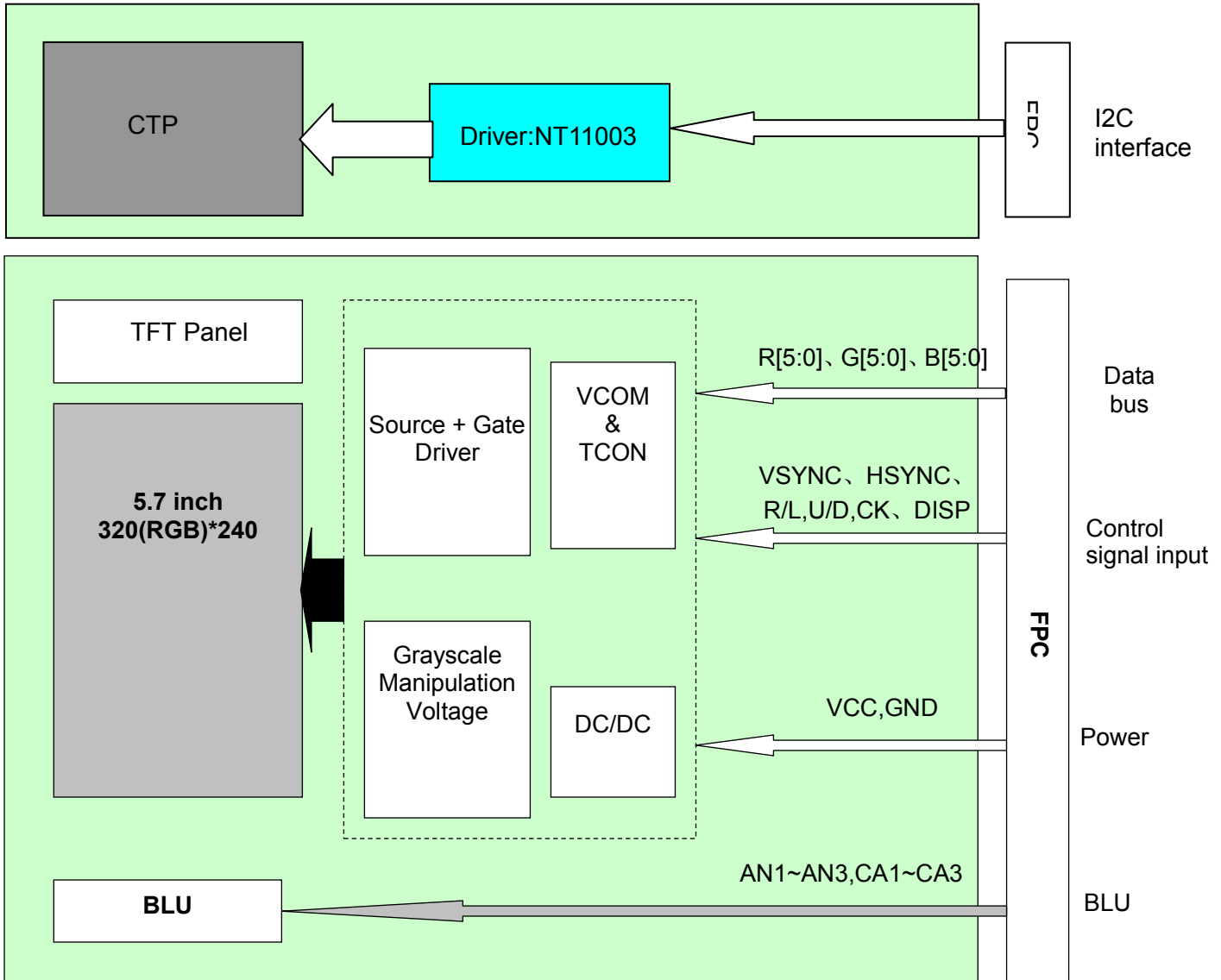
Note 1: I_F is defined for one channel LED. There are total three LED channels in back light unit. Under LCM operating, the stable forward current should be inputted.

Note 2: Optical performance should be evaluated at $T_a=25^{\circ}C$ only.

Note 3: If LED is driven by high current, high ambient temperature & humidity condition. The life time of LED will be reduced. Operating life means brightness goes down to 50% initial brightness. Typical operating life time is estimated data.



5 .Block Diagram



6.TFT LCDTiming Chart

6.1 SYNC Mode

VDD=3.3V Ta=25°C

Parameter	Symbol	Symbol	Min	Typ	Max	Unit
DOTCLK	DOTCLK frequency	Fclk	6.2	6.4	12.1	MHz
	DOTCLK cycle	Tclk	82.64	156.25	161.29	ns
Hsync	Horizontal display area	Thd	320	320	320	Tclk
	1 horizontal line	Th	406	408	560	Tclk
	Hsync pulse width	Thpw	1	-	-	Tclk
	Horizontal blanking	Thb	70	70	70	Tclk
	Horizontal front porch	Thfp	16	18	170	Tclk
Vsync	Frame rate	-	-	60	65	Hz
	Vertical display area	Tvd	240	240	240	Th
	Vsync period time	Tv	254	263	360	Th
	Vsync pulse width	Tvpw	1	-	-	Th
	Vsync blanking	Tvb	13	13	13	Th
	Vsync front porch	Tvfp	1	10	107	Th

6.2 DE Mode

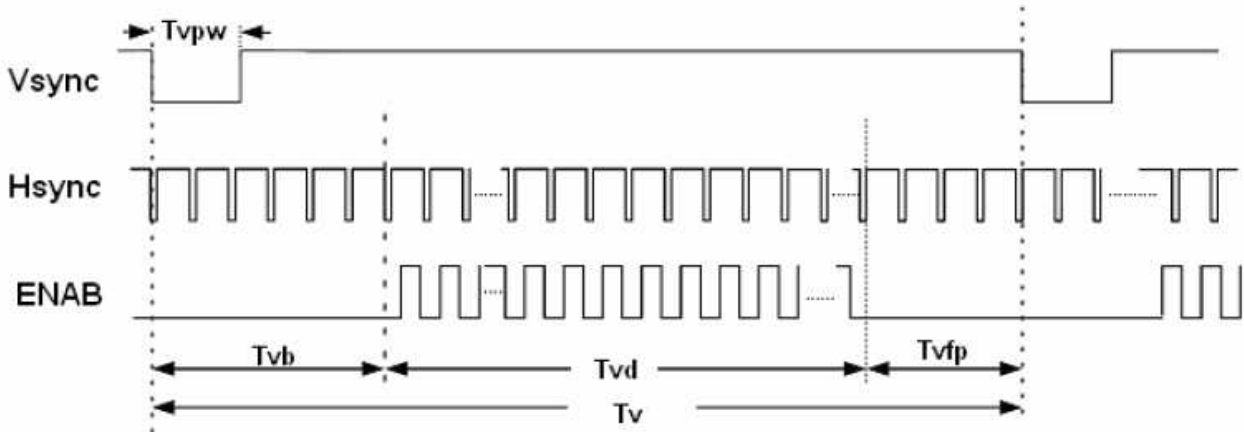
VDD=3.3V Ta=25°C

Description		Symbol	Min.	Typ.	Max.	Unit
DOTCLK frequency		Fclk	6.2	6.4	12.1	MHz
Horizontal section	Horizontal total	Th	406	408	560	Tclk
	H Total blank	Thb+Thfp	86	88	240	Tclk
	Valid Data Width	Thd	320	320	320	Tclk
Vertical section	Frame rate	-	-	60	65	Hz
	Vertical total	Tv	254	263	360	Th
	V total blank	Tvb+Tvfp	14	23	120	Th
	Valid Data Width	Tvd	240	240	240	Th

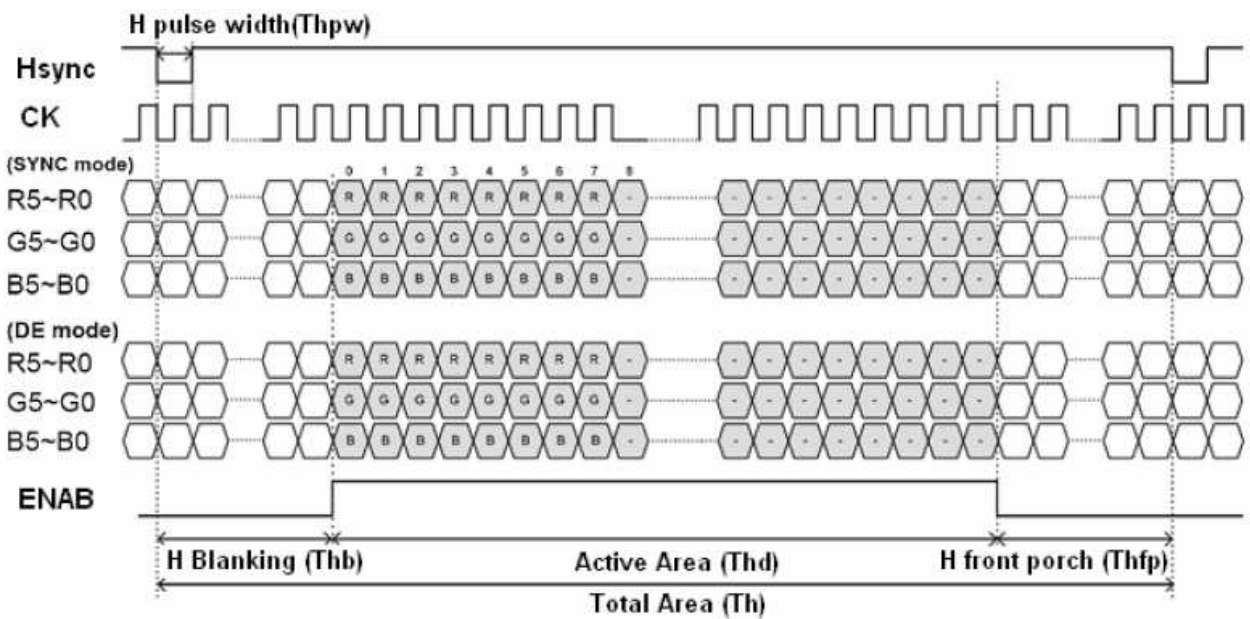
Note: The LCM could auto-detect which mode is working.

6.3 Timing Diagram

6.3.1 Vertical Input Timing

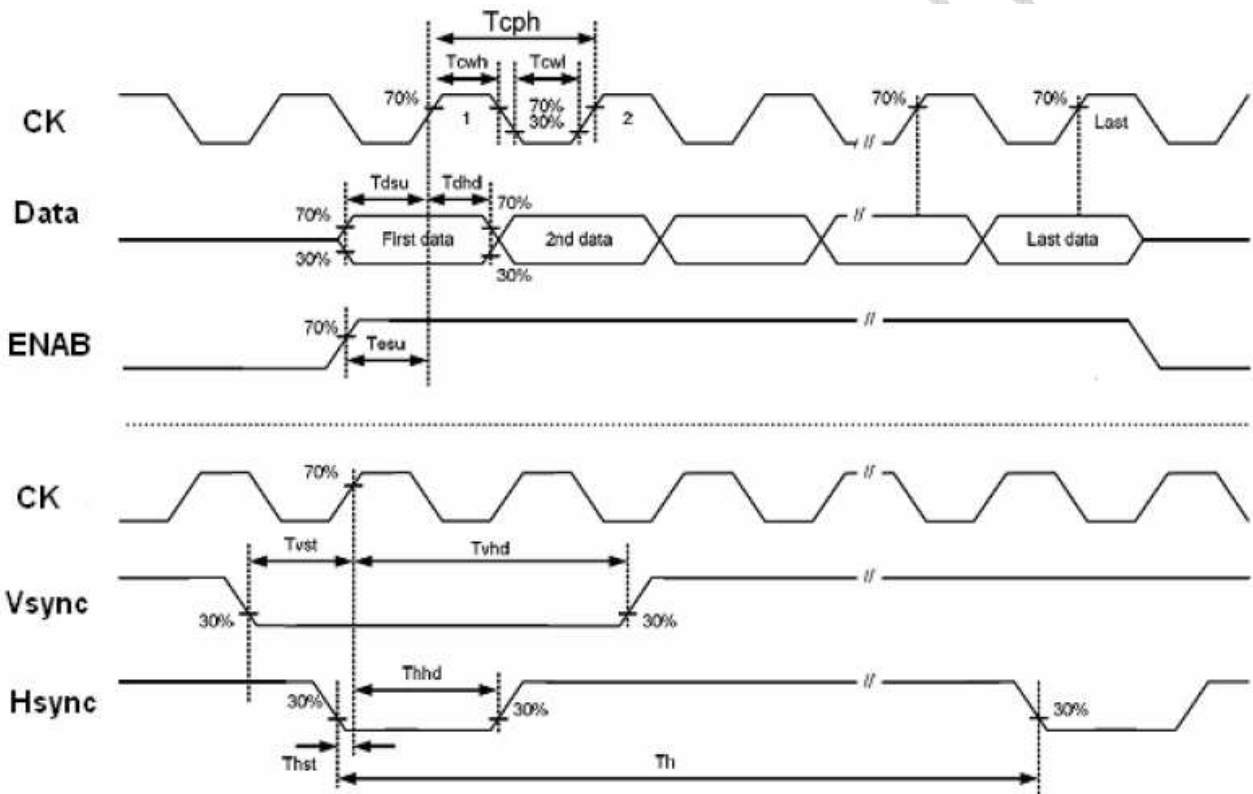


6.3.2 Horizontal Input Timing



6.4 AC Input characteristics

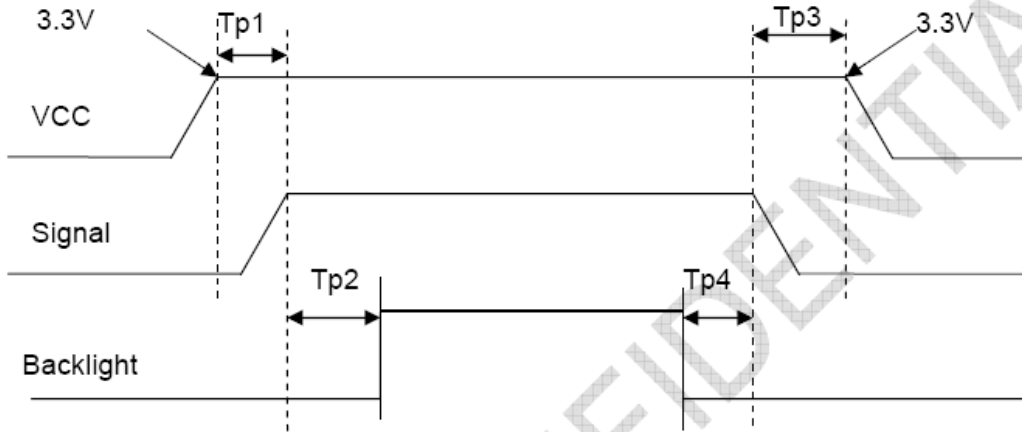
Parameter	Symbol	Min	Typ	Max	Unit	Conditions
DOTCLK pulse duty	Tcwh	40%	50%	60%	Tclk	Tcph is DCLK cycle
VSYNC setup time	Tvst	10	-	-	ns	
VSYNC hold time	Tvhd	10	-	-	ns	
HSYNC setup time	Thst	10	-	-	ns	
HSYNC hold time	Thhd	10	-	-	ns	
Data setup time	Tdsu	10	-	-	ns	Rn, Gn, Bn to DCLK
Data hold time	Tdhd	10	-	-	ns	Rn, Gn, Bn to DCLK
Enable setup time	Tesu	10			ns	



6.5 Power ON/OFF Sequence

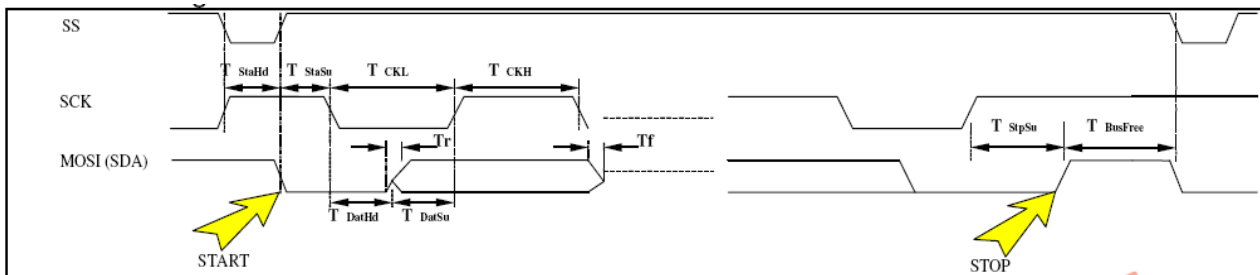
Item	Symbol	Min	Typ	Max	Unit	Remark
VCC 3.0V to signal starting	Tp1	5	-	50	ms	
Signal starting to backlight on	Tp2	50	-	-	ms	
Signal off to VCC 3.0V	Tp3	0	-	50	ms	
Backlight off to signal off	Tp4	50	-	-	ms	

Table 5.5 Power on/off sequence



7. CTP Timing

7.1 I2C interface

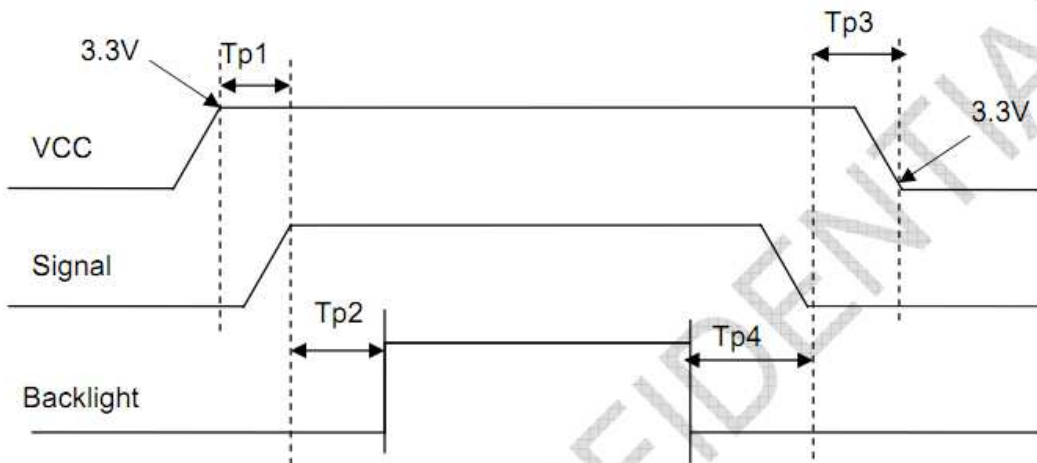


Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
I ² C Clock	F _{CLK}			400	KHZ	V _{DD} =V _{DDIO} =3.3V, T _A =25°C
I ² C Clock Low	T _{CKL}	1300			nS	V _{DD} =V _{DDIO} =3.3V, T _A =25°C
I ² C Clock High	T _{CKH}	600			nS	V _{DD} =V _{DDIO} =3.3V, T _A =25°C
I ² C Data Rising Time	T _r			300	nS	V _{DD} =V _{DDIO} =3.3V, T _A =25°C
I ² C Data Falling Time	T _f			300	nS	V _{DD} =V _{DDIO} =3.3V, T _A =25°C
I ² C Data Hold Time	T _{DatHd}	0			nS	V _{DD} =V _{DDIO} =3.3V, T _A =25°C
I ² C Data Setup Time	T _{DatSu}	100			nS	V _{DD} =V _{DDIO} =3.3V, T _A =25°C
I ² C Start Condition Hold Time	T _{StaHd}	600			nS	V _{DD} =V _{DDIO} =3.3V, T _A =25°C
I ² C Start Condition Setup Time	T _{StaSu}	600			nS	V _{DD} =V _{DDIO} =3.3V, T _A =25°C
I ² C Stop Condition Setup Time	T _{StpSu}	600			nS	V _{DD} =V _{DDIO} =3.3V, T _A =25°C
I ² C Bus Free Time	T _{BusFree}	1300			nS	V _{DD} =V _{DDIO} =3.3V, T _A =25°C

7.2 Power ON Sequence

Item	Symbol	Min	Typ	Max	Unit	Remark
VCC 3.0V to signal starting	Tp1	5	-	50	ms	
Signal starting to backlight on	Tp2	50	-	-	ms	
Signal off to VCC 3.0V	Tp3	5	-	50	ms	
Backlight off to signal off	Tp4	50	-	-	ms	

Table 5.5 Power on/off sequence



8. Optical Characteristics

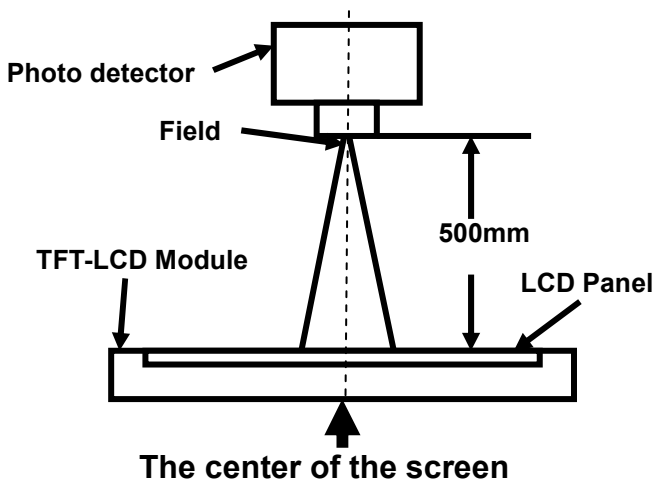
Item	Symbol	Condition	Min	Typ	Max	Unit	Remark
View Angles	θT	$CR \geq 10$	60	70	--	Degree	Note 2
	θB		50	60	--		
	θL		60	70	--		
	θR		60	70	--		
Contrast Ratio	CR	$\theta = 0^\circ$	400	500	--		Note1 Note3
Response Time	T_{ON}	25°C	--	20	30	ms	Note1 Note4
	T_{OFF}						
Chromaticity	White	Backlight is on	x	0.274	0.324	0.374	Note5 Note1
			y	0.279	0.362	0.379	
	Red		x	0.566	0.616	0.666	
			y	0.303	0.353	0.403	
	Green		x	0.285	0.335	0.385	
			y	0.526	0.576	0.626	
	Blue		x	0.086	0.136	0.186	
			y	0.076	0.126	0.176	
Uniformity	U		75	80	--	%	Note1、Note6
NTSC			45	50	--	%	
Luminance	L		300	400	--	cd/m ²	Note7
Reflectivity					4	%	Note8
HAZE					2	%	Note8

Test Conditions:

- $I_F = 25\text{mA}$ (one channel), the ambient temperature is 25°C.
- The test systems refer to Note 1 and Note 2.

Note 1: Definition of optical measurement system.

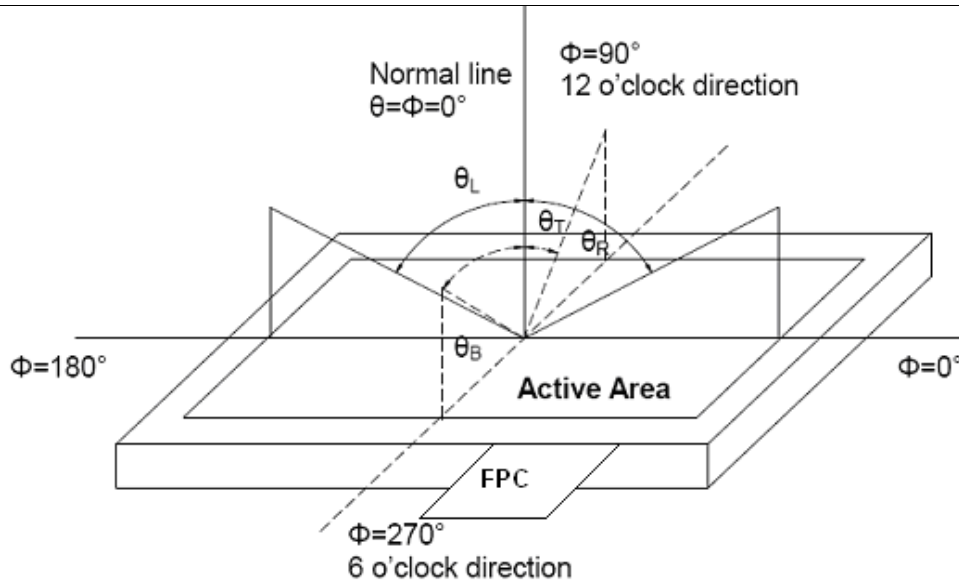
The optical characteristics should be measured in dark room. After 10 Minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Item	Photo detector	Field
Contrast Ratio	SR-3A	1°
Luminance		
Chromaticity		
Lum Uniformity		
Response Time	BM-7A	2°

Note 2: Definition of viewing angle range and measurement system.

viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).



Note 3: Definition of contrast ratio

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD is on the "White" state}}{\text{Luminance measured when LCD is on the "Black" state}}$$

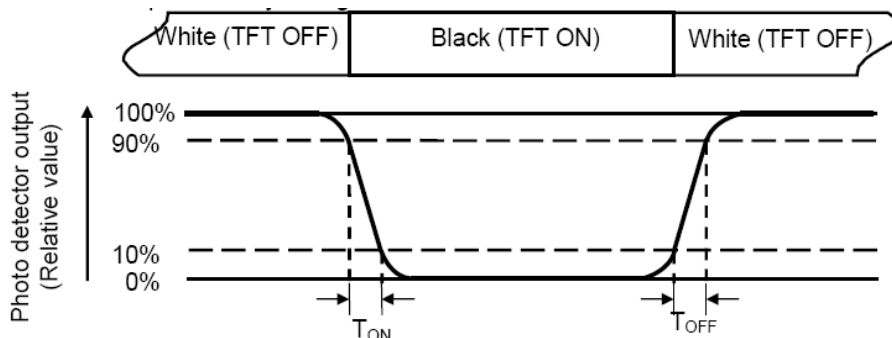
“White state “: The state is that the LCD should drive by V_{white}.

“Black state”: The state is that the LCD should drive by V_{black}.

V_{white}: To be determined V_{black}: To be determined.

Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between “White” state and “Black” state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

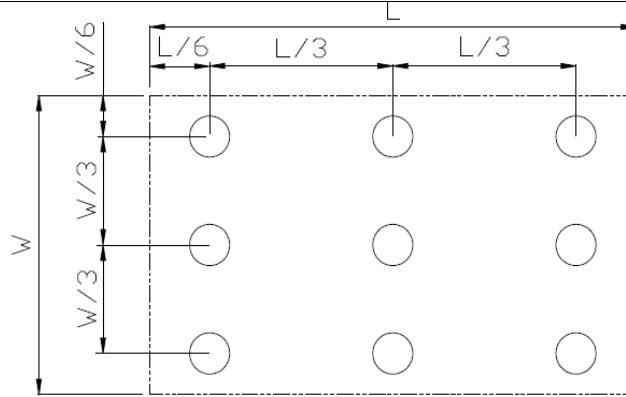
Color coordinates measured at center point of LCD.

Note 6: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer Fig. 2). Every measuring point is placed at the center of each measuring area.

$$\text{Luminance Uniformity (U)} = \text{Lmin} / \text{Lmax}$$

L-----Active area length W----- Active area width



Lmax: The measured Maximum luminance of all measurement position.

Lmin: The measured Minimum luminance of all measurement position.

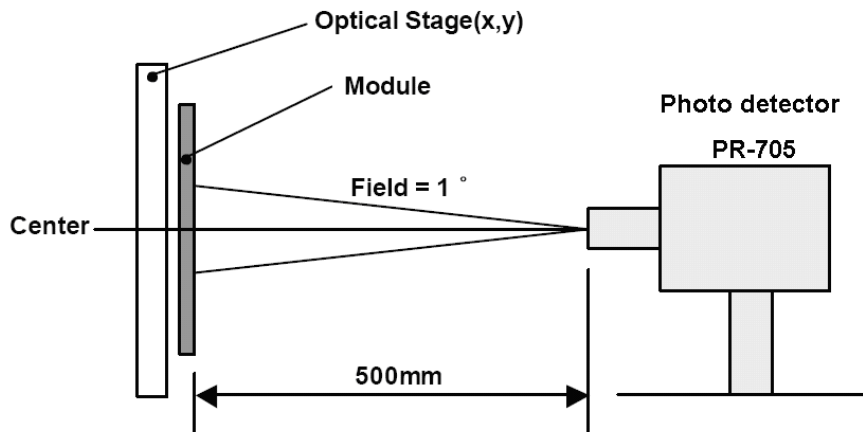
Note 7: Definition of Luminance:

Measure the luminance of white state at center point on the CTP

Note8: Measuring equipments: DMS-501, PR-705. @550nm

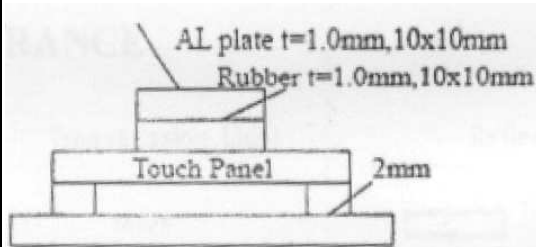
Measuring condition:

- After stabilizing and leaving the panel alone at a given temperature for 30 min, the measurement should be executed,
- Measuring surroundings: a stable, windless and dark room,
- Measuring temperature: $T_a=25^{\circ}\text{C}$,
- 30 min after lighting the back-light.



Note2: conform to National standard GB2410—80 /ASTM D1003—61(1997)

9. Reliability Test

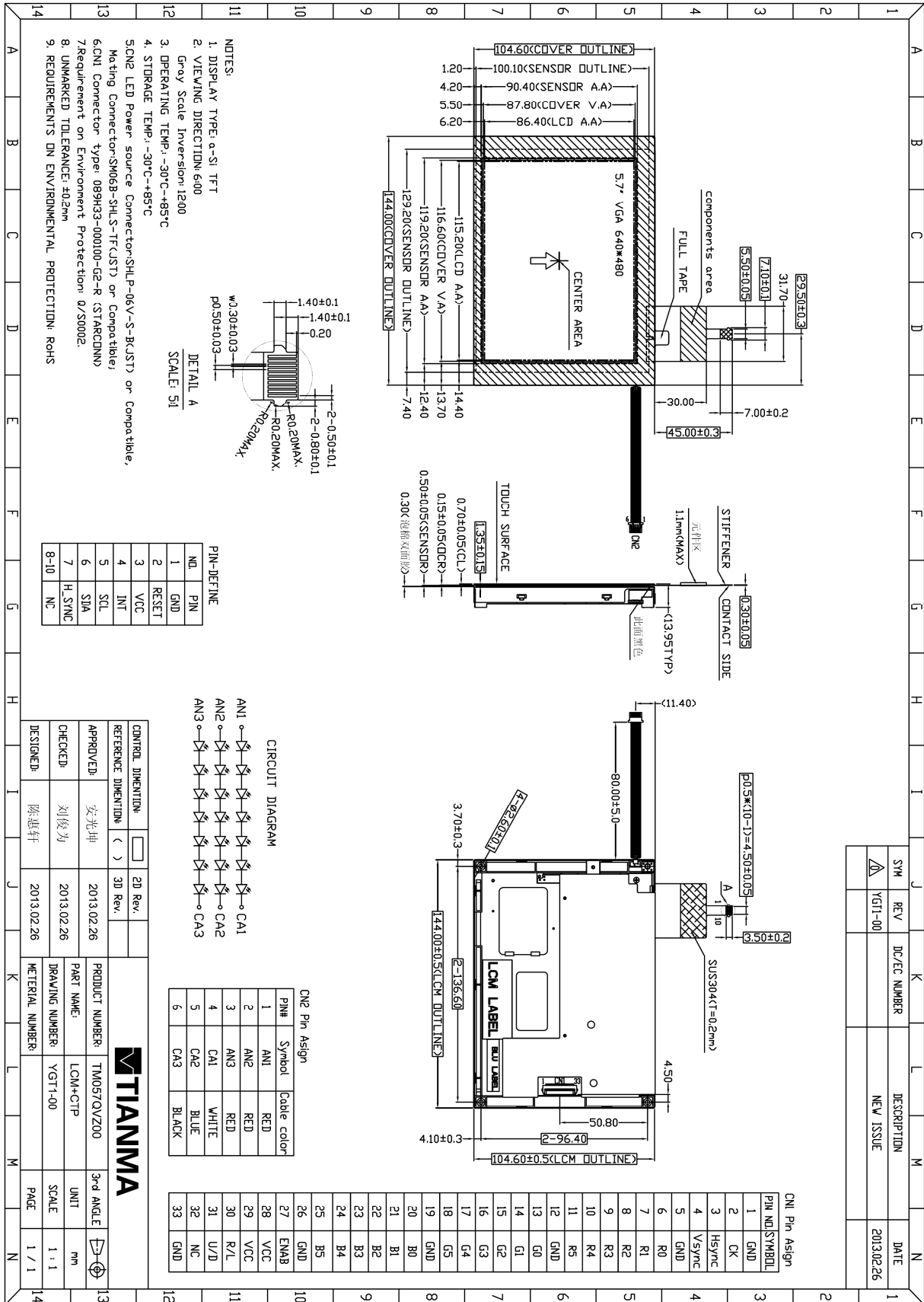
No	Test Item	Condition	Remarks
1	High Temperature Operation	Ta = +70°C, 120 hours	Note1,Note6,Note7 IEC60068-2-1,GB2423.2
2	Low Temperature Operation	Ta = -20°C, 120 hours	Note1, Note7,IEC60068-2-1 GB2423.1
3	High Temperature Storage	Ta = +80°C, 120 hours	Note1, Note7,Note8 IEC60068-2-1 GB2423.2
4	Low Temperature Storage	Ta = -30°C, 96 hours	Note1, Note7,EC60068-2-1 GB2423.1
5	High Temperature & Humidity Storage	Ta=+65°C、RH=90%, 120 hours	Note1,Note3, Note4,Note7 IEC60068-2-78 GB/T2423.3
6	Thermal Shock/ Solder Joint Life Test	-30°C (30min) ⇔ 80°C (30min) ,Change Time:5min,100cycle	Note1,Note9 Start with cold temperature End with high temperature, IEC60068-2-14,GB2423.22
12	ESD	C=150pF、R=330Ω Air: ±8KV Contact:±4KV 5times (Environment:15°C~35°C, 30%~60%.86Kpa~106Kpa)	Note2,Note5, IEC61000-4-2 GB/T17626.2
13	Shock Test	Half Sine Wave 60G ,6ms,±X,±Y,±Z 3times for each direction	Note2
14	Drop Test(package state)	Height:60cm, 1corner,3edges,6surfaces	Note2,IEC60068-2-32 GB/T2423.8
15	Surface hardness	6H	JIS-K5600
16	Static Load Resistance Test	After 4.5Kg load for 1min is applied to the center area (1.0cm ²) of the Touch panel, the requirements in optical characteristic and electrical characteristics shall be satisfied. 	No crack after test.

17	Drop ball test	Use the 64g steel (ϕ 25) ball is dropped on the Glass surface from 70cm height at 1time(Glass side)	No crack after test.
18	Terminal Pull Test	$\pm 90^\circ$ direction, weight:500g, non-operation	Function is OK

Notes:

1. The test result shall be evaluated after the sample has been left at room temperature and humidity for 2 hours without load. No condensation shall be accepted. The sample will not be accepted if appear these defects:
 - 1).Air bubble in the LCD;
 - 2).Seal leak
 - 3).Non-display
 - 4).missing segments
 - 5).Glass crack
 - 6).CR reduction >40%
 - 7).IDD increase >100%
 - 8).Brightness reduction >50%
 - 9).Color coordinate tolerance >0.05
2. The samples of these tests will not be accepted if appear these defects:
 - 1).Air bubble in the LCD;
 - 2).Seal leak
 - 3).Non-display
 - 4).missing segments
 - 5).Glass crack
3. Each test item applies for a test sample only once, The test sample can not be used again in any other test item.
- 4.For Damp Proof Test, Pure water(Resistance > 10M Ω) should be used.
- 5.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- 6 In the test of High Temperature Operation and High Temperature & Humidity Operation ,the operation temperature is the surface temperature of module
- 7 High Temperature Operation、 Low Temperature Operation、 High Temperature Storage、 Low Temperature Storage、 High Temperature & Humidity Operation、 High Temperature & Humidity Storage will be increased the test time to 1000hours in the same conditions to test out the ability of module, and we can not guarantee that the module will not fail during 1000hours.These items test only once
- 8.Thermal Shock will be changed the cycle to 1000cycles to test out the ability of module, and we can not guarantee that the module will not fail after the test. This item test only once

10. Mechanical Drawing



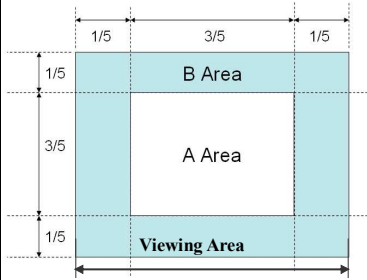
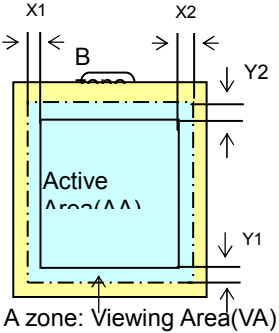
11. Product Inspection Criteria

11.1 Classification of defects

Major defects (MA): A major defect refers to a defect that may substantially degrade usability for product applications, including all functional defects (such as no display, abnormal display, open or missing segment, short circuit, missing component), outline dimension beyond the drawing, progressive defects and those affecting reliability.

Minor defects (MI): A minor defect refers to a defect which is not considered to be able to substantially degrade the product application or a defect that deviates from existing standards almost unrelated to the effective use of the product or its operation, such as black spot, white spot, bright spot, pinhole, black line, white line, contrast variation, glass defect, polarizer defect, etc.

11.2 Definition of inspection range

<p>For dot defect of TFT LCD which is not smaller than 3 inches, dividing three areas to make a judgment (according to figure 1).</p> <p>A area : center of viewing area B area : periphery of viewing area C area : Outside viewing area</p> <p>For other defects, dividing two areas to make a judgment (according figure 2).</p> <p>A zone : Inside Viewing area B zone : Outside Viewing area</p> <p>X1(A.A~V.A): 0mm X2(A.A~V.A): 0mm Y1(A.A~V.A): 0mm Y2(A.A~V.A): 0mm</p>	 <p>Figure 1</p>
	 <p>Figure 2</p>

11.3 Inspection items and general notes

General notes	① Should any defects which are not specified in this standard happen, additional standard shall be determined by mutual agreement between customer and TIANMA. ② Viewing area should be the area which TIANMA guarantees. ③ Limit sample should be prior to this Inspection standard. ④ Viewing judgment should be under static pattern. ⑤ Inspection conditions Inspection distance: 250 mm (from the sample) Temperature : 25±5 °C Inspection angle : 45 degrees in 12 o'clock direction (all defects in viewing area should be inspected from this direction)	
Inspection items	Pinhole, Bright spot, Black spot, White spot, Black line, White Line, Foreign particle, Bubble	The color of a small area is different from the remainder. The phenomenon doesn't change with voltage
	Contrast variation	The color of a small area is different from the remainder. The phenomenon changes with voltage
	Polarizer defect	Scratch, Dirt, Particle, Bubble on polarizer or between polarizer and glass
	Dot defect (TFT LCD)	The pixel appears bright or dark abnormally when display
	Functional defect	No display, Abnormal display, Open or missing segment, Short circuit, False viewing direction

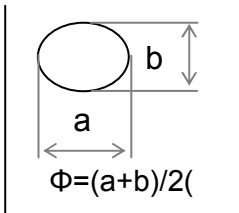
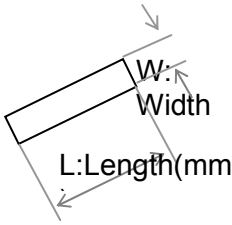
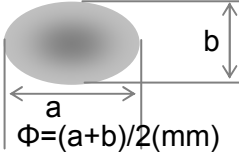
	Glass defect	Glass crack, Shaved corner of glass, Surplus glass
	PCB defect	Components assembly defect

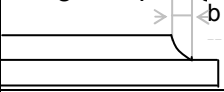
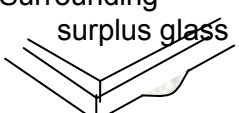
11.4 Outgoing Inspection level

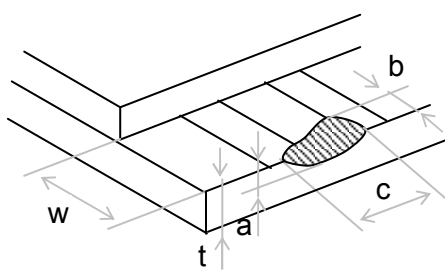
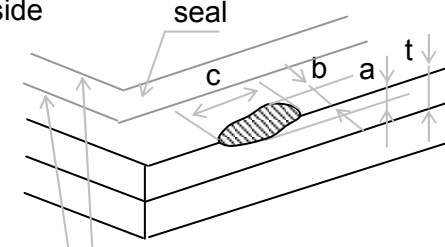
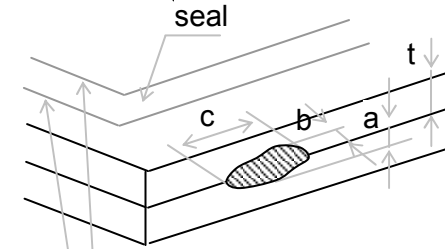
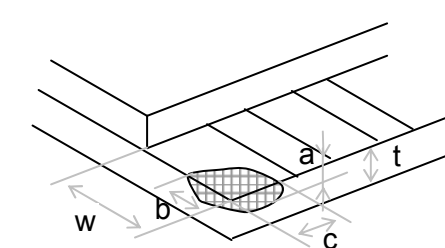
Outgoing Inspection standard	Inspection conditions	Inspection				
		Min.	Max.	Unit	IL	AQL
Major Defects	See 9.3 general notes	See	11.5		II	0.65
Minor Defects	See 9.3 general notes	See	11.5		II	1.5

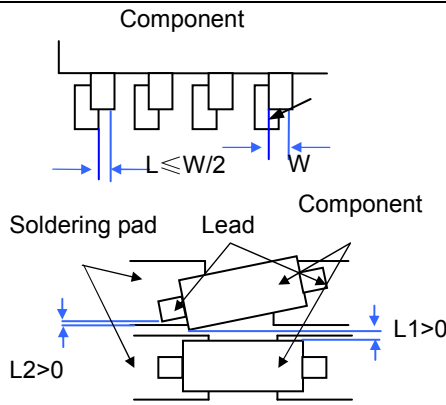
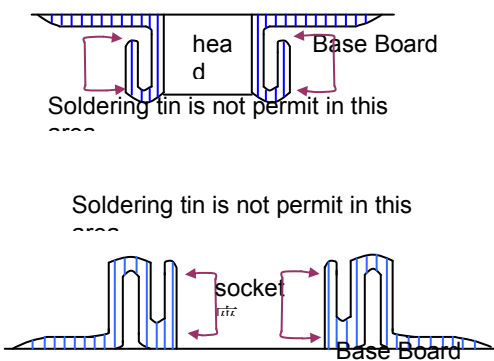
Note : Sampling standard conforms to GB2828

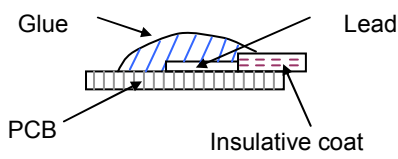
11.5 Inspection Items and Criteria

Inspection items			Judgment standard					
			Category		Acceptable number			
					A zone	B zone		
1	Black spot, White spot, Bright Spot, Pinhole, Foreign Particle, Particle in or on glass, Scratch on glass		A	$\Phi \leq 0.10$	Neglected			
			B	$0.10 < \Phi \leq 0.15$	2			
			C	$0.15 < \Phi \leq 0.20$	1			
			D	$0.20 < \Phi$	0			
			Total defective point(B,C)		3		Neglected	
2	Black line, White line, and Particle Between Polarizer and glass, Scratch on glass		A	$W \leq 0.01$	Neglected			
			B	$0.01 < W \leq 0.03$ $L \leq 3.0$	2			
			C	$0.03 < W \leq 0.05$ $L \leq 3.0$	1			
			D	$0.05 < W$	0			
			Total defective point(B,C)		3		Neglected	
3	Contrast variation		A	$\Phi \leq 0.2$	Neglected			
			B	$0.2 < \Phi \leq 0.3$	2			
			C	$0.3 < \Phi \leq 0.4$	1			
			D	$0.4 < \Phi$	0			
			Total defective point(B,C)		3		Neglected	
4	Dot defect (if TFT LCD is smaller than 3 inches)		LCD Class	Defect	A area	B area		
			A	Bright dot	1	Neglected		

	used)			Dark dot		2	d	
				Total		2		
				B	Bright dot			2
					Dark dot			3
					Total			4
		TFT LCD between 3~10.4 inches	LCD Class	Defect		A area	B area	Neglected
				A	Bright dot		1	
			Dark dot		1	2		
			Total		4			
			B	Bright dot		2	2	
Dark dot				2	3			
Total		6						
Notes: Bright dot: in R、G、B or dark display figure, the pixel appears bright. Dark dot: in R、G、B or white display figure, the pixel appears dark. Defect area must be less than an half size of the dot.								
5	Bubble inside cell	any size		none	none	none		
6	Polarizer defect (if Polarizer is used)	Scratch ,damage on polarizer, Particle on polarizer or between polarizer and glass.	Refer to item 1 and item 2.					
			Bubble, dent and convex	A	$\Phi \leq 0.3$	Neglected	Neglected	
		B		$0.3 < \Phi \leq 0.7$	2			
		C		$0.7 < \Phi$	0			
7	Surplus glass	Stage surplus glass	 $b \leq 0.3\text{mm}$					
		Surrounding surplus glass	 Should not influence outline dimension and assembling.					
8	Open segment or open common	Not permitted						
9	Short circuit	Not permitted						
10	False viewing direction	Not permitted						
11	Contrast ratio uneven	According to the limit specimen						
12	Crosstalk	According to the limit specimen						
13	Black /White spot(display)	Refer to item 1						
14	Black /White line(display)	Refer to item 2						

Inspection items		Judgment standard		Acceptable number		
		Category(application: B zone)				
15	Glass defect crack	①The front of lead terminals	A	$a \leq t$, $b \leq 1/5W$, $c \leq 3\text{mm}$	Max.3 defects allowed	
			B	Crack at two sides of lead terminals should not cover patterns and alignment mark		
			②Surrounding crack—non-contact side	 <p>Inner border line of the Outer border line of the</p>		$b < \text{Inner border line of the seal}$
		③ Surrounding crack— contact side	 <p>Inner border line of the Outer border line of the</p>			$b < \text{Outer border line of the seal}$
		④Corner	A	$a \leq t$, $b \leq 3.0$, $c \leq 3.0$		
			B	Glass crack should not cover patterns u and alignment mark and patterns.		

Inspection items		Judgment standard	
		Category(application: B zone)	
16	PCB defect	<p>Component soldering: No cold soldering · short · open circuit · burr · tin ball The flat encapsulation component position deviation must be less than 1/3 width of the pin (Pic.1) ; the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2)</p>	<p>Component</p> 
		<p>lead defect: The lead lack must be less than 1/3 of its width; The lead burr must be less than 1/3 of the seam; Impurities connect with the near leads is not permitted</p>	
		<p>Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted</p>	

	<p>Glue on root of the speaker receiver and motor lead: The insulative coat of the lead must join into the PCB; the protected glue must envelop to the insulative coat.</p>	
--	---	--

12. Precautions for Use of LCD Modules

12.1 Handling Precautions

- 12.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 12.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 12.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 12.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 12.1.5 If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
- Isopropyl alcohol
 - Ethyl alcohol
- Solvents other than those mentioned above may damage the polarizer.
- Especially, do not use the following:
- Water
 - Ketone
 - Aromatic solvents
- 12.1.6 Do not attempt to disassemble the LCD Module.
- 12.1.7 If the logic circuit power is off, do not apply the input signals.
- 12.1.8 To prevent destruction of the elements by static electricity, be careful to maintain

an optimum work environment.

- a. Be sure to ground the body when handling the LCD Modules.
- b. Tools required for assembly, such as soldering irons, must be properly ground.
- c. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
- d. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

12.2 Storage precautions

10.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.

10.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature : 0°C ~ 40°C

Relatively humidity: ≤80%

10.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.

12.3 The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.

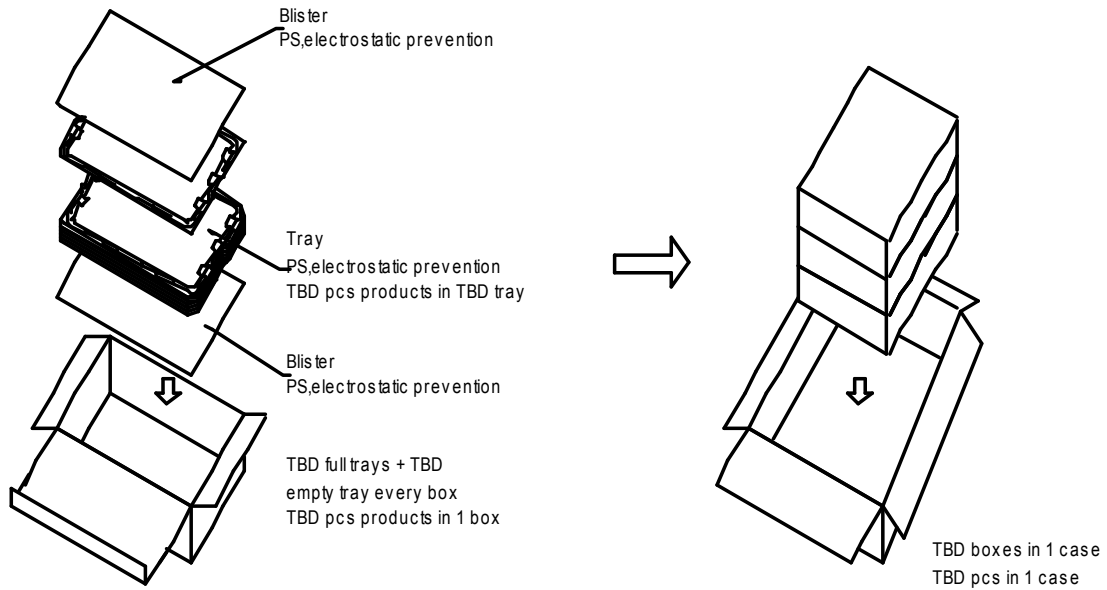
13.Packing Drawing(Reference)

TIANMA MICROELECTRONICS CO.

Packing Standards:

Quantity of products to be packed
Outlook size(Carton size):TBD

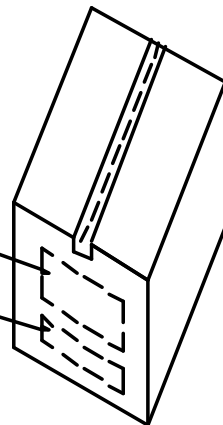
packed in a case: TBD pcs



Package Sign:

Case Mark
Remark
BMS
P.O.No.
PartNo.
QTY
CTN.No.
TTL.CTN.No.
MADE IN CHINA

Package Sign
Care Mark



Care Mark



14. Module Part Numbering System

TM	057	Q	V	Z	G	00
①	②	③	④	⑤	⑥	⑦

NO.	Explanation
①	TIANMA module indicating
②	Screen inch:043=4.3inch 057=5.7inch 070=7inch 102=10.2inch
③	Resolution: 480x240(Delta) A 240x400(Stripe) L 640x240(Delta) B 400x240(Stripe) M 960x240(Delta) C 480x272(Stripe) N 96x64 (Stripe) D 480x234(Stripe) O 128x128(Stripe) E 320x480(Stripe) P 128x160(Stripe) F 480x640(Stripe) Q 176x220(Stripe) G 800x480(Stripe) R 240x320(Stripe) H 800x600(Stripe) S 240x240(Stripe) V 1024x768(Stripe) T 320x320(Stripe) J others X 320x240(Stripe) K

④	<p>Product structure:</p> <table border="1" data-bbox="571 250 1171 987"> <tr><td>TSP+BL(CCFL)+FPC+M4</td><td>A</td></tr> <tr><td>TSP+</td><td>B</td></tr> <tr><td>BL(CCFL)+FPC+M4</td><td>C</td></tr> <tr><td>BL(LED)+FPC+M4</td><td>D</td></tr> <tr><td>BL(LED)+FPC+M4.Dual Display</td><td>E</td></tr> <tr><td>FPC+M4</td><td>F</td></tr> <tr><td>M4</td><td>G</td></tr> <tr><td>M3</td><td>H</td></tr> <tr><td>M2</td><td>Y</td></tr> <tr><td>M1</td><td>J</td></tr> <tr><td>BL(CCFL)+FPC+M4+PCB</td><td>K</td></tr> <tr><td>BL(LED)+FPC+M4+PCB</td><td>L</td></tr> <tr><td>TSP+BL(CCFL)+FPC+M4+PCB</td><td>M</td></tr> <tr><td>TSP+BL(LED)+FPC+M4+PCB</td><td>N</td></tr> <tr><td>CTP+BL(LED)+FPC+M4</td><td>V</td></tr> <tr><td>Others</td><td>X</td></tr> </table> <p>M1:Panel(array+CF) M2:Panel(array+CF+LC) M3:Panel(array+CF+LC+PLZ) M4:Panel(array+CF+LC+PLZ+Driver)</p>	TSP+BL(CCFL)+FPC+M4	A	TSP+	B	BL(CCFL)+FPC+M4	C	BL(LED)+FPC+M4	D	BL(LED)+FPC+M4.Dual Display	E	FPC+M4	F	M4	G	M3	H	M2	Y	M1	J	BL(CCFL)+FPC+M4+PCB	K	BL(LED)+FPC+M4+PCB	L	TSP+BL(CCFL)+FPC+M4+PCB	M	TSP+BL(LED)+FPC+M4+PCB	N	CTP+BL(LED)+FPC+M4	V	Others	X
TSP+BL(CCFL)+FPC+M4	A																																
TSP+	B																																
BL(CCFL)+FPC+M4	C																																
BL(LED)+FPC+M4	D																																
BL(LED)+FPC+M4.Dual Display	E																																
FPC+M4	F																																
M4	G																																
M3	H																																
M2	Y																																
M1	J																																
BL(CCFL)+FPC+M4+PCB	K																																
BL(LED)+FPC+M4+PCB	L																																
TSP+BL(CCFL)+FPC+M4+PCB	M																																
TSP+BL(LED)+FPC+M4+PCB	N																																
CTP+BL(LED)+FPC+M4	V																																
Others	X																																
⑤	<p>Product assembly location:</p> <p>Shenzheng Z Shanghai H Chengdu C Wuhan W</p>																																
⑥	<p>Product application:</p> <p>Industry : G Consume: NA</p>																																
⑦	<p>Series Number:</p> <p>00,01,02,03.....</p>																																